

28th IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY

May 12-15, 2024 - Lisbon, Portugal



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IMPORTANT DATES

• Full Paper Submission: Dec 15th, 2023

• Notification of Acceptance: Jan 31st, 2024

• Final Paper Submission: Mar 15th, 2024

• Student Awards Application: Mar 15th, 2024

Early Bird Registration: Mar 15th, 2024

Sponsors Registration: Mar 22nd, 2024











Standing for almost three decades, the *IEEE Workshop on Signal and Power Integrity (SPI)* has evolved into a noteworthy forum of exchange on all aspects of Signal and Power Integrity, comprising the latest research and developments on design, characterization, modeling, simulation and testing at chip, package, board, and system level. The workshop brings together developers and researchers from academia and industry in order to encourage cooperation.

In view of previous years success, the Committees are hardworking on the 28th Edition which will be held as an in-person event at the *Portuguese Communications Foundation* in Lisbon, Portugal. The technical program will include both oral and poster sessions, and several prominent experts will be giving keynotes and tutorials on areas of emerging interest.

Follow us on *LinkedIn* and feel free to look into our website for further information about *SPI 2024*, as well as broadcast the workshop in your institution and to your fellow colleagues and students. It is a pleasure to invite you all to the *28th IEEE Workshop on Signal and Power Integrity* and we look forward to your contribution and participation!

CALL FOR PAPERS

<u>Paper Submission is open!</u> Original and unpublished contributions on all aspects of Signal and Power Integrity are welcomed, related to the following **topics** of interest:

- Modeling and simulation for SI/PI
- Coupled signal and power integrity analysis
- Noise reduction and equalization techniques
- · High-speed link design and modeling
- · Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-onchin
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures

- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- Al in electronics design

Accepted papers will be included in the workshop's program and submitted for inclusion into <u>IEEE Xplore</u>. Authors of the **best ranked accepted papers** will have the opportunity to submit an extended version of their work for publication in a special section of the <u>IEEE Transactions on Components</u>, Packaging and Manufacturing Technology.

AWARDS

- **BEST PAPER AWARD**: The *SPI 2024 Best Paper Award* will recognize the foremost paper among all papers submitted and presented during the workshop.
- BEST STUDENT PAPER AWARD & IEEE EPS STUDENT TRAVEL GRANTS: The Student Awards aim to encourage graduate students to attend the workshop and present their current research work.



